

03-04-1999



OVER SHEET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

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To the Honorable Commissioner of Patents and Trademarks

and the attached original documents or copy thereof

83-91-2

1. Name of Conveying Part(ies):

Vishnu K. Agarwal
Gurtej S. Sandhu

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):

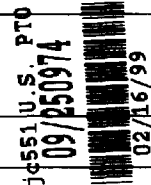
Name: Micron Technology, Inc.

Internal Address:

Street Address: 8000 South Federal Way

City: Boise State: ID Zip: 83706-9632

Additional names(s) & address(es) attached: Yes No



3. Nature of conveyance:

- Assignment Security Agreement
- Merger Change of Name
- Other _____

Execution Date: January 29, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: January 29, 1999

A. Patent Application No.(s):

B. Patent No.(s)

Additional numbers attached: Yes No

Additional numbers attached: Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David G. Latwesen, Ph.D.

Internal Address:
Wells, St. John, Roberts,

Gregory & Matkin P.S.

Street Address: 601 W. First Avenue, Ste. 1300

City: Spokane State: WA Zip: 99201-3828

6. Total number of applications and patents involved. 1

7. Total fee (37 CFR 3.41). \$40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number
23-0925

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

03/01/1999 MAILING 00000042 09250974

04 FC 581 David G. Latwesen, Ph.D. DP

Name of Person Signing

Signature

2/16/99

Date

TOTAL NUMBER OF PAGES INCLUDING COVER SHEET, ATTACHMENTS AND DOCUMENT: 5

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ASSIGNMENTPARTIES TO THE ASSIGNMENT:INVENTORS:

Vishnu K. Agarwal

Gurtej S. Sandhu

ASSIGNEE:

Micron Technology, Inc.
Corporation of the State of Delaware
8000 South Federal Way
Boise, Idaho 83706-9632

BACKGROUND OF THIS ASSIGNMENT:

INVENTORS have conceived certain new and useful inventions disclosed in a United States patent application titled Methods of Forming Materials Comprising Tungsten and Nitrogen, and Methods of Forming Capacitors.

MICRON TECHNOLOGY, INC. desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

THE PARTIES AGREE AS FOLLOWS:

In consideration of good and valuable consideration, the receipt sufficiency and adequacy of which is hereby acknowledged, INVENTORS hereby sell, assign and transfer to MICRON TECHNOLOGY, INC. the entire right, title and interest in the above-identified application executed currently

1 with this assignment and to any reissues, renewals, divisions or continuations
2 thereof, and hereby authorizes the Commissioner of Patents and Trademarks
3 to issue such Letters Patent to MICRON TECHNOLOGY, INC., for the sole
4 use of MICRON TECHNOLOGY, INC., its successors or assigns.

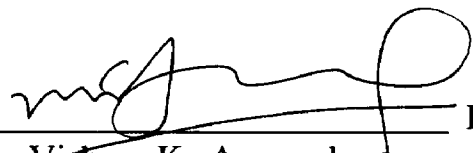
5 INVENTORS further agree to execute, at the request and expense of
6 MICRON TECHNOLOGY, INC. such other formal documents as may be
7 required to fully convey the interest transferred herein and will similarly
8 execute any application papers required for the filing of any division,
9 continuation, renewal or reissue of the patent application or resulting Letters
10 Patent; and will generally do everything necessary or desirable to obtain and
11 enforce proper protection for the inventions assigned hereby.

12 INVENTORS further assign to MICRON TECHNOLOGY, INC. the
13 whole right, title and interest in the inventions disclosed in the application
14 throughout all countries foreign to the United States. MICRON
15 TECHNOLOGY, INC. is hereby authorized to apply for patents relating to
16 the inventions in its own name in countries where such procedure is proper;
17 to claim the benefit of the International Convention; to file and prosecute
18 International Applications relating to the inventions under the Patent
19 Cooperation Treaty; and to file and prosecute applications relating to the
20 inventions under the European Patent Convention. INVENTORS agree to
21 execute applications relating to the inventions in those countries and under
22 those conventions where it is necessary that the same be executed by the
23 inventor, and to execute assignments of such applications and the resulting

1 Letters Patent to MICRON TECHNOLOGY, INC. as well as all other
2 necessary papers in relation to such applications and Letters Patent.

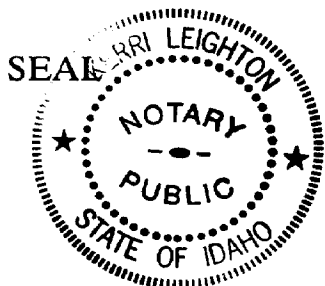
3 INVENTORS further warrant and covenant that no assignment, grant,
4 mortgage, license or other agreement affecting the rights and property herein
5 conveyed has been or will be made to others by the undersigned, and that the
6 full rights to convey the same as herein expressed is possessed by the
7 undersigned.


8 To be binding on the heirs, assigns, representatives and successors of
9 the undersigned and extend to the successors, assigns and nominees of the
10 Assignees.

11 (Signature)  Date: 1/28/99
12 Vishnu K. Agarwal

13 State of Idaho)
14 County of Ada) ss.

15 BEFORE ME, this 28 day of January 1999 personally
16 appeared the above-named inventor, to me known to be the person who is
17 described in and who executed the foregoing assignment instrument and
18 acknowledged to me that he/she executed the same of his/her own free will
19 for the purpose therein expressed.



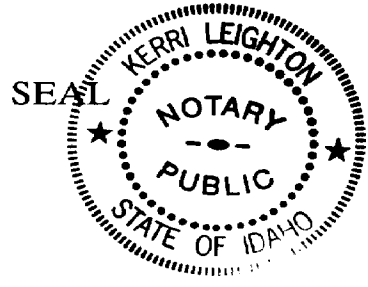
19 
20 Notary or Consular Officer
21 My Commission Expires: 1/9/2002

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(Signature) Gurtej Singh Sandhu Date: 1/29/99
Gurtej S. Sandhu

State of Idaho)
County of Ada) ss.

BEFORE ME, this 29 day of January 1999 personally appeared the above-named inventor, to me known to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he/she executed the same of his/her own free will for the purpose therein expressed.



Kerri Leighton
Notary or Consular Officer
My Commission Expires: 1/9/2002